

**COMPLETE LISTING OF ALL OF THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claims 1-7 (Previously canceled)

Claims 8-12 (Canceled)

Claim 13 (Original): An assembled substrate, comprising a substrate having a first side and a second side, and a first electrical contact area on said first side and a second electrical contact area on said second side;

an electrical component having a plurality of leads electrically connected to said first electrical contact area of said substrate; and

a capacitor plate electrically connected to said second electrical contact area on said second side of said substrate substantially opposite said first electrical contact area of said substrate.

Claim 14 (Original): The assembled substrate of claim 13, wherein said assembled substrate further comprises:

a first interposer between said component and said first electrical contact area on said first side of said substrate; and

a second interposer between said capacitor plate and said second electrical contact area on said second side of said substrate.

Claim 15 (previously presented): The assembled substrate of claim 14, wherein said first interposer and said second interposer are chosen from a group consisting of: a socket, or a conductive elastomeric material.

Claim 16 (previously presented): The assembled substrate of claim 13, wherein said substrate is chosen from a group consisting of: a PCB, an MCM, and a flexible substrate.

Claim 17 (previously presented): The assembled substrate of claim 13, wherein said component is chosen from a group consisting of: an LGA component, or a BGA component.

Claim 18 (Original): The assembled substrate of claim 13, wherein said capacitor plate has a plurality of layers of dielectric material separating a plurality of layers of conductive material.

Claim 19 (previously presented): The assembled substrate of claim 13, wherein said capacitor plate comprises:

a plurality of conductive power planes; and  
style="padding-left: 40px;">a plurality of conductive ground planes, wherein said plurality of conductive power planes and said plurality of conductive ground planes are separated by one or more dielectric layers including a dielectric layer chosen from the materials comprising at least one of: FR4, a resin, an elastomeric material, or a ceramic.

Claim 20 (original): The assembled substrate of claim 13, wherein said capacitor plate is attached by solder to said second electrical contact area on said second side of said substrate.

Claims 21-29 (Canceled)